

SPECIFICATION

REFOND P/N

RF-A3H10-WYSP-E5

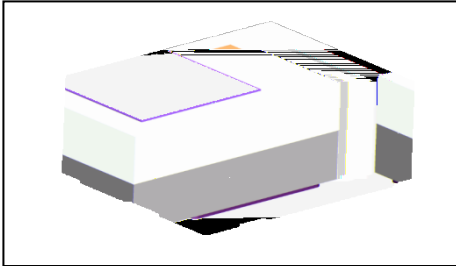
R&D
Mass Production

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1. Description

1.1 General Description



This product uses the ceramics package, it has a high reliability. it also be widely application for Automotive Exterior Lighting. Size(mm): 2.00X1.60X0.80mm.

2.00X1.60X0.80mm

1.2 Features

- ▶ Ceramic Package.
- ▶ High Power Output and High Luminance.
- ▶ Pb-free reflow soldering application.
- ▶ Moisture sensitive level:Level2. Level 2
- ▶ RoHS compliant. RoHS

1.3 Application

- ▶ Automotive Exterior Lighting, Cornering Light.

1.4 Package Dimension

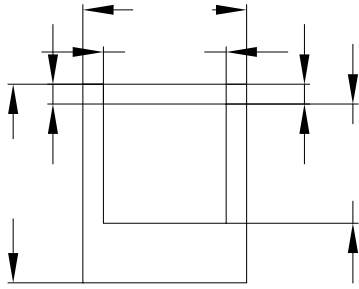


Fig.1-1 Top View

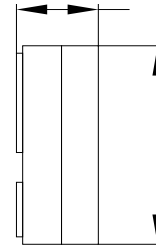


Fig.1-2 Side View

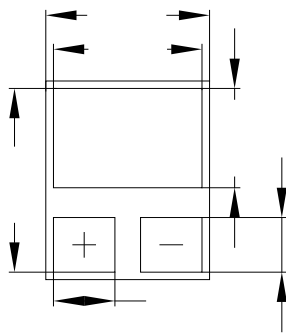


Fig.1-3 Bottom View

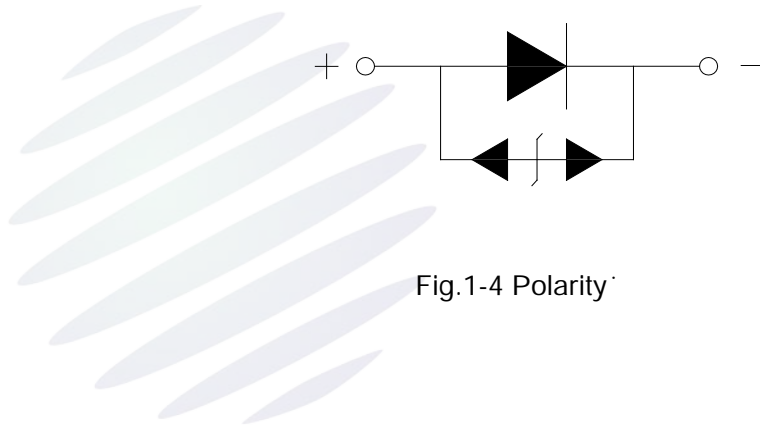


Fig.1-4 Polarity

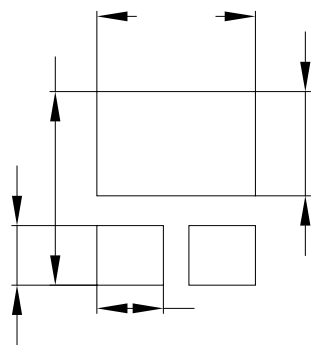


Fig.1-5 Soldering Patterns

Notes

All dimensions units are millimeters.

All dimensions tolerances are $\pm 0.2\text{mm}$ unless otherwise noted.

±

Notes

1. 1/10 Duty cycle, 0.1ms pulse width. 0.1ms 1/10.
2. The above forward voltage measurement allowance tolerance is $\pm 0.1V$. $\pm 0.1V$
3. The above color coordinates measurement allowance tolerance is 0.003. 0.003
4. The above luminous flux measurement allowance tolerance $\pm 10\%$. $\pm 10\%$.
5. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.
6. All measurements were made under the standardized environment of Refond.
7. When the LEDs are in operation the maximum current should be decided after measuring the package temperature. Junction temperature should not exceed the maximum rate. LED

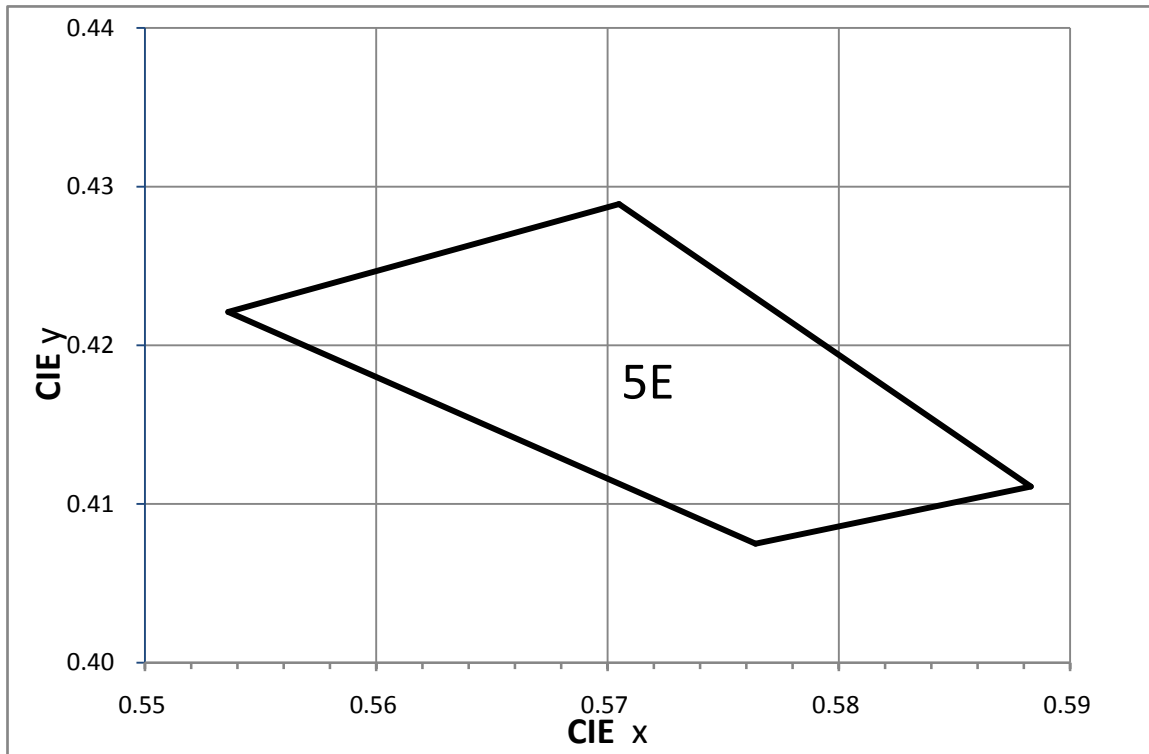
1.6 Bin Range Of Forward Voltage and Luminous Flux (IF=1000mA)

BIN (IF=1000mA)

Table 1-3

V _F (V)	G0	H0	I0	J0	/	/
	2.8-3.0	3.0-3.2	3.2-3.4	3.4-3.6	/	/
Φ(lm)	TB	UA	UB	/	/	/
	144-160	160-177	177-196	/	/	/

The Chromaticity Diagram



Bin data:

BIN CODE	X1	Y1	X2	Y2	X3	Y3	X4	Y4
5E	0.5536	0.4221	0.5764	0.4075	0.5883	0.4111	0.5705	0.4289

1.7 Typical optical characteristics curves

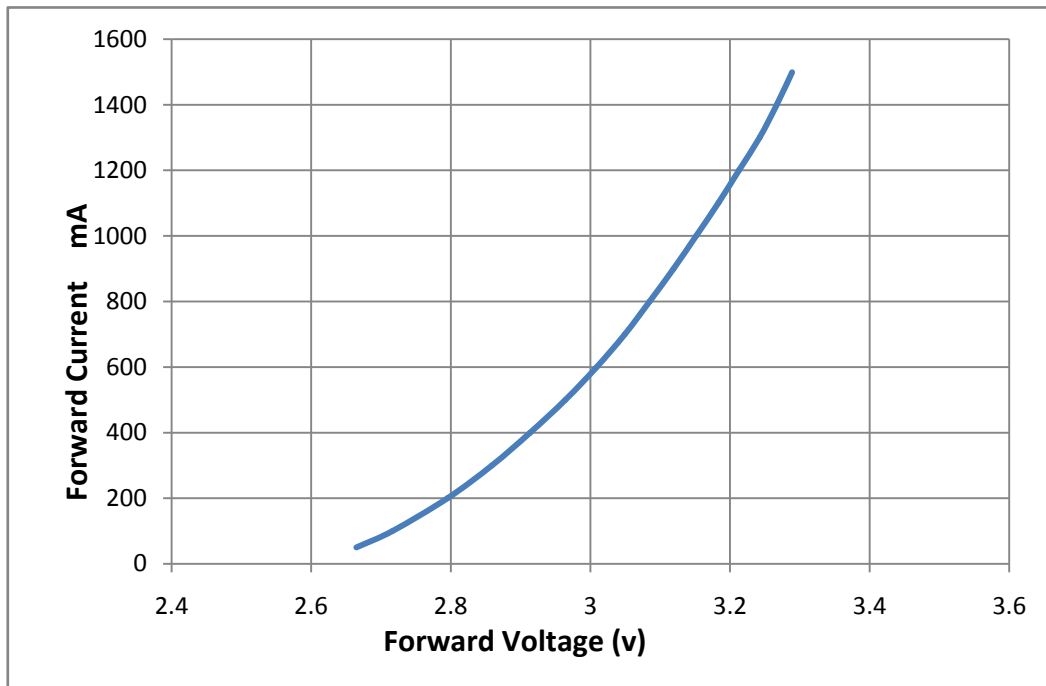


Fig 1-6 Forward Voltage Vs. Forward Current

Fig 1-7 Forward Current Vs. Relative Intensity

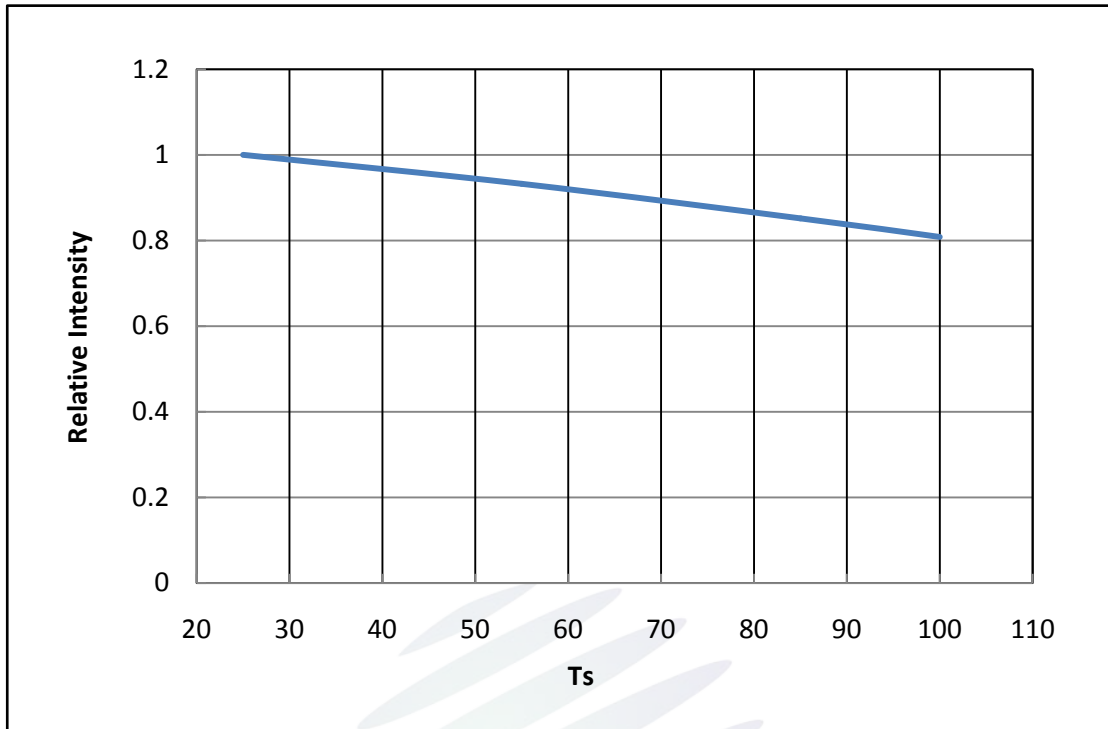


Fig 1-8 Ts Temperature Vs Relative Intensity

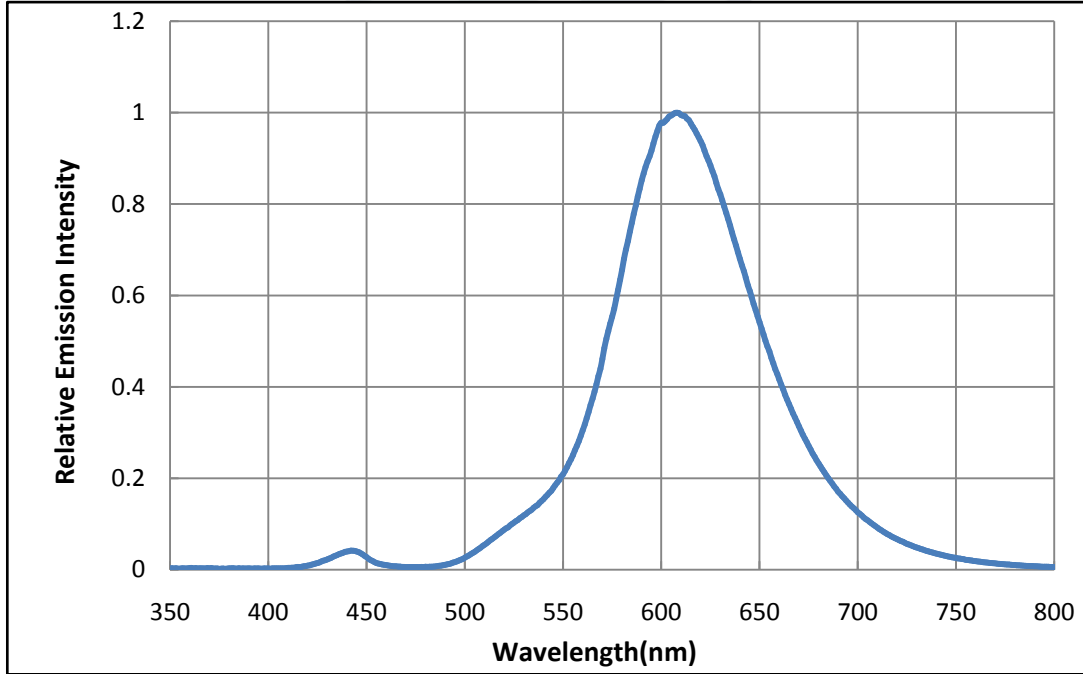


Fig 1-9 Spectrum Distribution

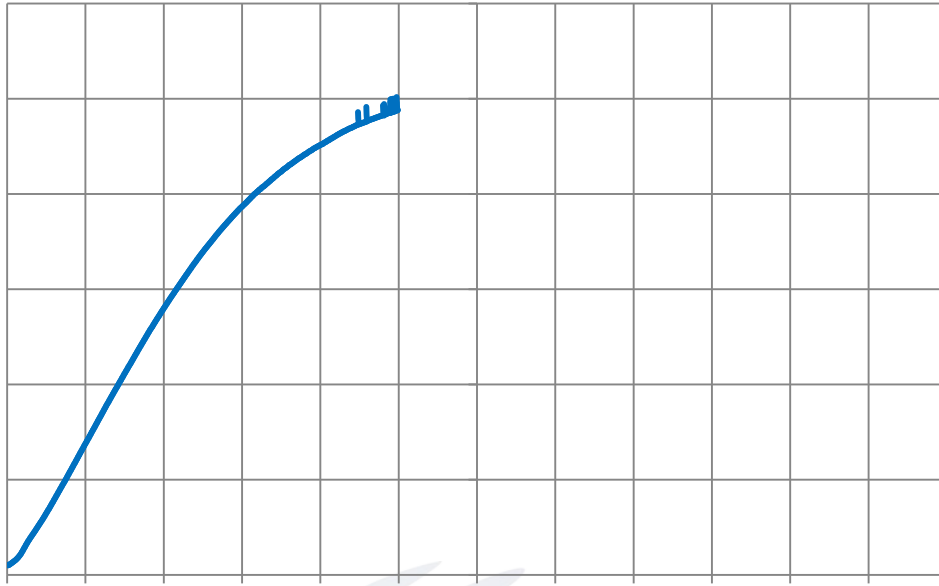


Fig 1-10 Radiation diagram



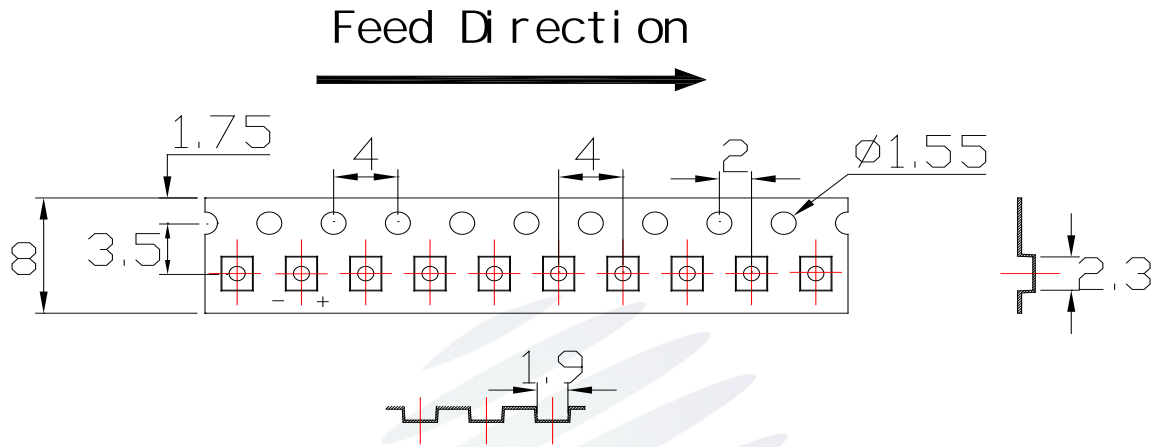
Fig 1-11 Ts Temperature Vs Forward Current

2. Packaging

2.1 Packaging Specification

Package:4000pcs/reel.

2.1.1 Carrier Tape Dimension



2.1.3 Label Form Specification

Table 2-2 Label Form Specification

Fig 2-3 Label Form Specification

2.2 Moisture Resistant Packing



Fig.2- Moisture Resistant PacJ 0. ()29337 0 Td +0B47.2753 <</M-0.001 Tw 0.279 01 Tw



2.5 Criteria For Judging Damage

Table Criteria For Judging Damage

Test Items	Symbol	Test Condition	Criteria For Judgement	
			Min.	Max.
Forward Voltage	V_F	$I_F=1000\text{mA}$	-	U.S.L*)x1.1
Reverse Current	I_R	$V_R = 5V$	-	U.S.L*)x2.0
Luminous Flux 光通量	-	$I_F=1000\text{mA}$	L.S.L*)x0.7	-

Notes

- 1.U.S.L: Upper standard level L.S.L: Lower standard level
2. The above reliability tests is based on the verification of a single/strip LED of Refond's existing experimental platform, the reliability experiment was taken under good heat dissipation conditions. when customers applies the LED to the series and parallel circuit, should take consideration of all the factors such as the current, voltage distribution, heat dissipation and others. LED
- 3.The technical information shown in the data sheets are limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license.

3. SMT Reflow Soldering Instructions SMT

3.1 SMT Reflow Soldering Instructions SMT

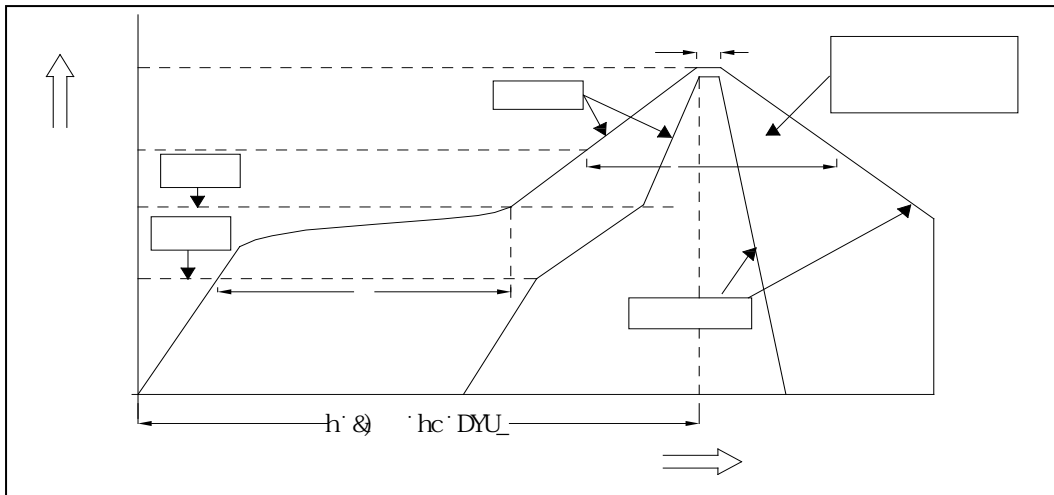


Fig.3-1 SMT Reflow Soldering Instructions SMT

Table 3-1 SMT Reflow Soldering Instructions SMT

Average temperature rise speed	T_{smx}	T_p	3 °C/	Max 3 °C/ s
Preheating: minimum temperature	(T _{sm})		150 °C	
Preheating: Max temperature	(T _{smx})		200 °C	
Preheating: Time	T _{sm}	T _{smx}	60 - 120	60s-120s
Time limited to maintain high temperature: the temperature (T _l)	217 °C			
Time limited to maintain high temperature: The Time (t _l)	60 Max 60s			
Peak /Classification of temperature / (T _p)	260 °C			
Time limit classification of peak temperature time	10 Max 10s			
Hold time within 5 °C with the actual peak temperature (T _p) (T _p) 5 °C	30 Max 30s			
Cooling speed	6 °C/ Max 6 °C/ s			
Needed time from 25 °C to T _p 25 °C	8 Max 8 minutes			

Notes

(1) Reflow soldering should not be done more than two times. In the case of more than 24 hours passed soldering after first, LEDs will be damaged.

LED

(2) When soldering , do not put stress on the LEDs during heating.

3.1.1 Soldering Iron

(1) When hand soldering, keep the temperature of iron below less 300 less than 3 seconds

The hand solder should be done only one time.

3.1.2 Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or will not be damaged by repairing.

LED

LED

3.1.3 Cautions

The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be influence to the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when use the picking up nozzle, the pressure on the silicone resin should be proper. LED LED

(2) Components should not be mounted on warped (non coplanar) portion of PCB. After soldering, do not warp the circuit board.LED

(3) Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering.

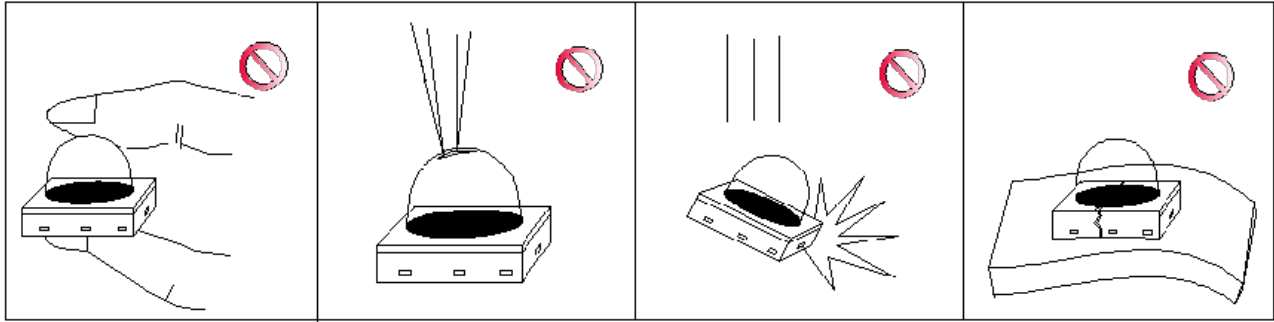


Fig 4-1

(5) In designing a circuit, the current through each LED must not exceed the absolute maximum rating specified for each LED. In the meanwhile, resistors for protection should be applied, otherwise slight voltage shift will cause big current change, burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration can be generated resulting in LED damage.

LED

LED

(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color change and so on. Please consider the heat generation of the LEDs when making the system design.

LED

(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the LED.

LED

Table 4-1 Storage

Conditions		Temperature	Humidity	Time
Storage	Before Opening Aluminum Bag	30	75%	Within 1 Year From Date
	After Opening Aluminum Bag	30	60%	168hours 168
Baking		60± 5	-	24hours 24

(8) If the moisture absorbent material silica gel has faded away or the LEDs have exceeded the storage time baking treatment should be performed after unpacking and based on the following condition 60 5 for above 24 hours.

±

If the package is flatulence or damaged, please notify the sales staff to assist.

(9) Similar to most Solid state devices; LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS). LED

(10) Other points for attention, please refer to our relevant information.



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Declare

This specification is written both in English and in Chinese and the latter is formal.